

# M29F040

## SINGLE SUPPLY 4 Megabit (512K x 8, Sector Erase) FLASH MEMORY

- FAST ACCESS TIME: 70ns
- 5V ± 10% SUPPLY VOLTAGE for PROGRAM and ERASE OPERATIONS
- 5V ± 10% SUPPLY VOLTAGE in READ OPERATIONS
- BYTE PROGRAMMING TIME: 10µs typical
- ERASE TIME
  - Sector: 1.0 sec typical
  - Bulk: 2.5 sec typical
- PROGRAM/ERASE CONTROLLER (P/E.C.)
  - Program Byte-by-Byte
  - Data Polling and Toggle Protocol for P/E.C. Status
- MEMORY ERASE in SECTORS
  - 8 Sectors of 64K Bytes each
  - Sector Protection
  - Multisector Erase
- ERASE SUSPEND and RESUME MODES
- 100,000 PROGRAM/ERASE CYCLES per SECTOR
- LOWPOWER CONSUMPTION
  - 25µA typical in Standby current
  - 8mA typical Read Current
  - Automatic CMOS Standby Mode



A0-A18	Address Inputs
DQ0-DQ7	Data Input / Outputs
Ē	Chip Enable
G	Output Enable
$\overline{W}$	Write Enable
Vcc	Supply Voltage
Vss	Ground



#### Figure 1. Logic Diagram



#### Figure 2A. LCC Pin Connections



Figure 2C. TSOP Reverse Pin Connections





#### DESCRIPTION

The M29F040 is a non-volatile memory that may be erased electrically at the sector level, and programmed Byte-by-Byte.

The interface is directly compatible with most microprocessors. PLCC32 and TSOP32 (8 x 20mm) packages are available. Both normal and reverse pin outs are available for the TSOP32 package.

#### Organisation

The FLASH Memory organisation is 512K x 8 bits with Address lines A0-A18 and Data Inputs/Outputs DQ0-DQ7. Memory control is provided by Chip Enable, Output Enable and Write Enable Inputs.

Erase and Program are performed through the internal Program/Erase Controller (P/E.C.).

Data Outputs bits DQ7 and DQ6 provide polling or toggle signals during Automatic Program or Erase to indicate the Ready/Busy state of the internal Program/Erase Controller.

#### Sectors

Erasure of the memory is in sectors. There are 8 sectors of 64K bytes each in the memory address space. Erasure of each sector takes typically 1.5 seconds and each sector can be programmed and erased over 100,000 cycles. Each sector may



Symbol	Parameter	Value	Unit
TA	Ambient Operating Temperature	-40 to 125	°C
T <sub>BIAS</sub>	Temperature Under Bias	-50 to 125	°C
T <sub>STG</sub>	Storage Temperature	–65 to 150	°C
$V_{10}$ <sup>(2)</sup>	Input or Output Voltages	-0.6 to 7	V
Vcc	Supply Voltage	–0.6 to 7	V
VA9 <sup>(2)</sup>	A9 Voltage	–0.6 to 13.5	V

#### Table 2. Absolute Maximum Ratings <sup>(1)</sup>

Notes: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the SGS-THOMSON SURE Program and other relevant quality documents.

2. Minimum Voltage may undershoot to -2V during transition and for less than 20ns.

separately be protected and unprotected against program and erase. Sector erasure may be suspended, while data is read from other blocks of the memory, and then resumed.

#### **Bus Operations**

Seven operations can be performed by the appropriate bus cycles, Read Array, Read Electronic Signature, Output Disable, Standby, Protect Sector, Unprotect Sector, and Write the Command of an Instruction.

#### **Command Interface**

Command Bytes can be written to a Command Interface (C.I.) latch to perform Reading (from the Array or Electronic Signature), Erasure or Programming. For added data protection, command execution starts after 4 or 6 command cycles. The first, second, fourth and fifth cycles are used to input a code sequence to the Command Interface (C.I.). This sequence is equal for all P/E.C. instructions. Command itself and its confirmation - if it applies - are given on the third and fourth or sixth cycles.

#### Instructions

Seven instructions are defined to perform Reset, Read Electronic Signature, Auto Program, Sector Auto Erase, Auto Bulk Erase, Sector Erase Suspend and Sector Erase Resume. The internal Program/Erase Controller (P/E.C.) handles all timing and verification of the Program and Erase instructions and provides Data Polling, Toggle, and Status data to indicate completion of Program and Erase Operations.

Instructions are composed of up to six cycles. The first two cycles input a code sequence to the Command Interface which is common to all P/E.C. instructions (see Table 7 for Command Descriptions). The third cycle inputs the instruction set up command instruction to the Command Interface. Subsequent cycles output Signature, Sector protection or the addressed data for Read operations. For added data protection, the instructions for program and sector or bulk erase require further command inputs. For a Program instruction, the fourth command cycle inputs the address and data to be programmed. For an Erase instruction (sector or bulk), the fourth and fifth cycles input a further code sequence before the Erase confirm command on the sixth cycle. Byte programming takes typically 10µs while erase is performed in typically 1.5 seconds.

Erasure of a memory sector may be suspended, in order to read data from another sector, and then resumed. Data Polling, Toggle and Error data may be read at any time, including during the programming or erase cycles, to monitor the progress of the operation. When power is first applied or if  $V_{CC}$  falls below  $V_{LKO}$ , the command interface is reset to Read Array.



#### Table 3. Operations

Operation	Ē	G	$\overline{w}$	DQ0 - DQ7
Read	VIL	VIL	VIH	Data Output
Write	VIL	VIH	VIL	Data Input
Output Disable	VIL	VIH	VIH	Hi-Z
Standby	VIH	Х	Х	Hi-Z

Note:  $X = V_{IL} \text{ or } V_{IH}$ 

Table 4. Electronic Signature

Code	Ē	G	w	A0	A1	A6	A9	Other Addresses	DQ0 - DQ7
Manufact. Code	VIL	VIL	VIH	V <sub>IL</sub>	VIL	VIL	VID	Don't Care	20h
Device Code	VIL	VIL	VIн	Vін	VIL	VIL	VID	Don't Care	0E2h

Table 5. Sector Protection Status

Code	Ē	G	W	A0	A1	A6	A16	A17	A18	Other Addresses	DQ0 - DQ7
Protected Sector	VIL	VIL	VIH	VIL	VIH	VIL	SA	SA	SA	Don't Care	01h
Unprotected Sector	VIL	VIL	VIH	VIL	VIH	VIL	SA	SA	SA	Don't Care	00h

Note: SA = Address of sector being checked

#### **DEVICE OPERATION**

#### Signal Descriptions

**A0-A18 Address Inputs.** The address inputs for the memory array are latched during a write operation. The A9 address input is used also for the Electronic Signature read and Sector Protect verification. When A9 is raised to  $V_{ID}$ , either a Read Manufacturer Code, Read Device Code or Verify Sector Protection is enabled depending on the combination of levels on A0, A1 and A6. When A0, A1 and A6 are Low, the Electronic Signature Manufacturer code is read, when A0 is High and A1 and A6 are Low, the Device code is read, and when A1 is High and A0 and A6 are low, the Sector Protection Status is read for the sector addressed by A16, A17, A18.

DQ0-DQ7 Data Input/Outputs. The data input is a byte to be programmed or a command written to

the C.I. Both are latched when Chip Enable  $\overline{E}$  and Write Enable  $\overline{W}$  are active. The data output is from the memory Array, the Electronic Signature, the Data Polling bit (DQ7), the Toggle Bit (DQ6), the Error bit (DQ5) or the Erase Timer bit (DQ3). Ouputs are valid when Chip Enable  $\overline{E}$  and Output Enable  $\overline{G}$  are active. The output is high impedance when the chip is deselected or the outputs are disabled.

 $\overline{\mathbf{E}}$  Chip Enable. The Chip Enable activates the memory control logic, input buffers, decoders and sense amplifiers.  $\overline{\mathbf{E}}$  High deselects the memory and reduces the power consumption to the standby level.  $\overline{\mathbf{E}}$  can also be used to control writing to the command register and to the memory array, while  $\overline{\mathbf{W}}$  remains at a low level. Addresses are then latched on the falling edge of  $\overline{\mathbf{E}}$  while data is latched on the rising edge of  $\overline{\mathbf{E}}$ . The Chip Enable must be forced to V<sub>ID</sub> during Sector Unprotect operations.



Table 6. Instructions (1)

Mne.	Instr.	Cyc.		1st Cyc.	2nd Cyc.	3rd Cyc.	4th Cyc.	5th Cyc.	6th Cyc.	7th Cyc.	
RST <sup>(3,9)</sup>	Reset	1+	Addr. <sup>(2,6)</sup>	х	Read Mer	Read Memory Array until a new write cycle is initiated.					
	Neoet		Data	0F0h							
RSIG <sup>(3)</sup>	Read Electronic			x5555h	x2AAAh	x5555h		ctronic Sigr			
	Signature	51	Data	0AAh	55h	90h	write cycle is initiated. See Note 4.			<b>e</b> 4.	
RSP <sup>(3)</sup>	Read Sector	3+	Addr. <sup>(2,6)</sup>	x5555h	x2AAAh	x5555h	Read Sector Protection until a new write cycle is initiated. See Note 5.			iew write	
	Protection		Data	0AAh	55h	90h					
PG	i Program 4		Addr. <sup>(2,6)</sup>	x5555h	x2AAAh	x5555h	Program Address	Read Data Polling or Toggl			
		•	Data	0AAh	55h	0A0h	Program Data	Bit until Program completes.			
SE	Sector Erase	6	Addr. <sup>(2,6)</sup>	x5555h	x2AAAh	x5555h	x5555h	x2AAAh	Sector Address	Additional Sector <sup>(7)</sup>	
			Data	0AAh	55h	80h	0AAh	55h	30h	30h	
BE	Bulk Erase	6	Addr. <sup>(2,6)</sup>	x5555h	x2AAAh	x5555h	x5555h	x2AAAh	x5555h	Note 8	
		•	Data	0AAh	55h	80h	0AAh	55h	10h		
ES	Erase	1	Addr. <sup>(2,6)</sup>	х				ad all the d		d from any	
	Suspend		Data	0B0h	sector(s) not being erased then Resume Erase.						
ER	Erase	1	Addr. <sup>(2,6)</sup>	х				until Erase	completes	or Erase	
	Resume		Data	30h	is suspended another time						

Notes: 1. Command not interpreted in this table will default to read array mode.

3. The first cycle of the RST, RSP or RSIG instruction is followed by read operations to read memory array, Status Register or

Electronic Signature codes. Any number of read cycles can occur after one command cycle. 4. Signature Address bits A0, A1, A6 at V<sub>IL</sub> will output Manufacturer code (20h). Address bits A0 at V<sub>IH</sub> and A1, A6 at V<sub>IL</sub> will output

Device code (0E2h). 5. Protection Address: A0, A6 at V<sub>IL</sub>, A1 at V<sub>IH</sub> and A16, A17, A18 within the sector to be checked, will output the Sector Protection status.

6. Address bits A16, A17, A18 are don't care for coded address inputs.

7. Optional, additional sectors addresses must be entered within a 80µs delay after last write entry, timeout status can be verified through DQ3 value. When full command is entered, read Data Polling or Toggle bit until Erase is completed or suspended. 8. Read Data Polling or Toggle bit until Erase completes.

9. A wait time of  $5\mu s$  is necessary after a Reset command, before starting any operation.



#### **DEVICE OPERATION** (cont'd)

 $\overline{\mathbf{G}}$  Output Enable. The Output Enable gates the outputs through the data buffers during a read operation.  $\overline{\mathbf{G}}$  must be forced to V<sub>ID</sub> level during Sector Protect and Sector Unprotect operations.

 $\overline{\mathbf{W}}$  Write Enable. This input controls writing to the Command Register and Address and Data latches. Addresses are latched on the falling edge of  $\overline{\mathbf{W}}$ , and Data Inputs are latched on the rising edge of  $\overline{\mathbf{W}}$ .

V<sub>CC</sub> Supply Voltage. The power supply for all operations (Read, Program and Erase).

 $V_{\text{SS}}$  Ground.  $V_{\text{SS}}$  is the reference for all voltage measurements.

#### Table 7. Commands

Hex Code	Command
00h	Invalid/Reserved
10h	Bulk Erase Confirm
30h	Sector Erase Resume/Confirm
80h	Set-up Erase
90h	Read Electronic Signature/ Sector protection Status
0A0h	Program
0B0h	Erase Suspend
0F0h	Reset

Table	8.	Status	Register
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DQ	Name	Logic Level	Definition	Note		
		' <b>1</b> '	Erase Complete	Indicates the P/E.C. status, check during		
7	7 Data Polling	,0,	Erase on Going	Program or Erase, and on completion before checking bits DQ5 for Program or		
	Folling	DQ	Program Complete	Erase Success.		
		DQ	Program on Going			
		'-1-0-1-0-1-0-1-'	Erase or Program on Going	Successive read output complementary		
6	Toggle Bit '-0-0-0-0-0-		Program ('0' on DQ6) Complete	data on DQ6 while Programming or Erase operations are going on. DQ6 remain at constant level when P/E.C. operations are		
		'-1-1-1-1-1-1-'	Erase or Program ('1' on DQ6) Complete	completed or Erase Suspend is acknowledged.		
5	Error Bit		Program or Erase Error	This bit is set to '1' if P/E.C. has exceded		
		·O'	Program or Erase on Going	the specified time limits.		
4		'1'				
-		'O'				
	<b>-</b>	'1'	Erase Timeout Period Expired	P/E.C. Erase operation has started. Only		
3	Erase Time Bit	'O'	Erase Timeout Period on Going	possible command entry is Erase Suspend (ES). An additional sector to be erased in parallel can be entered to the P/E.C.		
2	Reserved					
1	Reserved					
0	Reserved					

Notes: Logic level '1' is High, '0' is Low. -0-1-0-0-1-1-1-0- represent bit value in successive Read operations.



#### **Memory Sectors**

The memory sectors of the M29F040 are shown in Figure 5. The memory array is divided in 8 sectors of 64K bytes. Each sector can be erased separately or any combination of sectors can be erased simultaneously. The Sector Erase operation is managed automatically by the P/E.C. The operation can be suspended in order to read from any another sector, and then resumed.

Sector Protection provides additional data security. Each sector can be separately protected or unprotected against Program or Erase. Bringing A9 and  $\overline{G}$  to  $V_{ID}$  initiates protection, while bringing A9,  $\overline{G}$ and  $\overline{E}$  to  $V_{ID}$  cancels the protection. The sector affected during protection is addressed by the inputs on A16, A17, and A18. Unprotect operation affects all sectors.

#### Operations

Operations are defined as specific bus cycles and signals which allow Memory Read, Command Write, Output Disable, Standby, Read Status Bits, Sector Protect/Unprotect, Sector Protection Check and Electronic Signature Read. They are shown in Tables 3, 4, 5.

**Read.** Read operations are used to output the contents of the Memory Array, the Status Register or the Electronic Signature. Both Chip Enable  $\overline{E}$  and Output Enable  $\overline{G}$  must be low in order to read the output of the memory. The Chip Enable input also provides power control and should be used for device selection. Output Enable should be used to gate data onto the output independent of the device selection. The data read depends on the previous command written to the memory (see instructions RST and RSIG, and Status Bits).

Write. Write operations are used to give Instruction Commands to the memory or to latch input data to be programmed. A write operation is initiated when Chip Enable  $\overline{E}$  is Low and Write Enable  $\overline{W}$  is Low with Output Enable  $\overline{G}$  High. Addresses are latched on the falling edge of  $\overline{W}$  or  $\overline{E}$  whichever occurs last. Commands and Input Data are latched on the rising edge of  $\overline{W}$  or  $\overline{E}$  whichever occurs first.

**Output Disable.** The data outputs are high impedance when the Output Enable  $\overline{G}$  is High with Write Enable  $\overline{W}$  High.

**Standby.** The memory is in standby when Chip Enable E is High and Program/Erase Controller P./E.C. is Idle. The power consumption is reduced to the standby level and the outputs are high impedance, independent of the Output Enable  $\overline{G}$  or Write Enable W inputs.

Automatic Standby. After 150ns of inactivity and when CMOS levels are driving the addresses, the chip automatically enters a pseudo standby mode

where consumption is reduced to the CMOS standby value, while outputs are still driving the bus.

**Electronic Signature.** Two codes identifying the manufacturer and the device can be read from the memory, the manufacturer's code for SGS-THOM-SON is 20h, and the device code is E2h for the M29F040. These codes allow programming equipment or applications to automatically match their interface to the characteristics of the particular manufacturer's product. The Electronic Signature is output by a Read operation when the voltage applied to A9 is at  $V_{ID}$  and address inputs A1 and A6 are at Low. The manufacturer code is output when the Address input A0 is Low and the device code when this input is High. Other Address inputs are ignored. The codes are output on DQ0-DQ7. This is shown in Table 4.

The Electronic Signature can also be read, without raising A9 to  $V_{ID}$  by giving the memory the instruction RSIG (see below).

Sector Protection. Each sector can be separately protected against Program or Erase. Sector Protection provides additional data security, as it disables all program or erase operations. This mode is activated when both A9 and  $\overline{G}$  are set to V<sub>ID</sub> and the sector address is applied on A16, A17 and A18. Sector protection is programmed using a Presto F program like algorithm. Protection is initiated on the edge of  $\overline{W}$  falling to V<sub>IL</sub>. Then after a delay of 100 $\mu$ s, the edge of  $\overline{W}$  rising to V<sub>IH</sub> ends the protection operation. Protection verify is achieved by bringing  $\overline{G}$ ,  $\overline{E}$  and A6 to V<sub>IL</sub> while  $\overline{W}$  is at V<sub>IH</sub> and A9 at V<sub>ID</sub>. Under these conditions, reading the data output will yield 01h if the sector defined by the inputs on A16, A17 and A18 is protected. Any attempt to program or erase a protected sector will be ignored by the device.

Any protected sector can be unprotected to allow updating of bit contents. All sectors must be protected before an unprotect operation. Sector unprotect is activated when A9,  $\overline{G}$  and  $\overline{E}$  are at  $V_{\text{ID}}.$ The addresses inputs A6, A16, A12 must be maintained at VIH. Sector unprotect is performed through a Presto F Erase like algorithm. Unprotect is initiated by the edge of W falling to  $V_{IL}$ . After a delay of 10ms, the edge of  $\overline{W}$  rising to  $V_{IH}$  will end the unprotection operation. Unprotect verify is achieved by bringing  $\overline{G}$  and  $\overline{E}$  to  $V_{IL}$  while A6 and  $\overline{W}$  are at V<sub>IH</sub> and A9 at V<sub>ID</sub>. In these conditions, reading the output data will yield 00h if the sector defined by the inputs on A16, A17 and A18 has been successfully unprotected. All combinations of A16, A17 and A18 must be addressed in order to ensure that all of the 8 sectors have been unprotected. Sector Protection Status is shown in Table 5



Table 9.	<b>AC Measurement Conditions</b>
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	SRAM Interface Levels	EPROM Interface Levels
Input Rise and Fall Times	≤ 10ns	≤ 10ns
Input Pulse Voltages	0 to 3V	0.45V to 2.4V
Input and Output Timing Ref. Voltages	1.5V	0.8V and 2V



#### Figure 3. AC Testing Input Output Waveform



#### **Table 10.** Capacitance<sup>(1)</sup> ( $T_A = 25 \circ C$ , f = 1 MHz)

Symbol	Parameter	Test Condition	Min	Мах	Unit
CIN	Input Capacitance	$V_{IN} = 0V$		6	pF
Cout	Output Capacitance	V <sub>OUT</sub> = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

#### Instructions and Commands

The Command Interface (C.I.) latches commands written to the memory. Instructions are made up from one or more commands to perform Reset, Read Electronic Signature, Sector Erase, Bulk Erase, Program, Sector Erase Suspend and Erase Resume. Commands are made of address and data sequences. Addresses are latched on the falling edge of  $\overline{W}$  or  $\overline{E}$  and data is latched on the rising of  $\overline{W}$  or  $\overline{E}$ . The instructions require from 1 to 6 cycles, the first or first three of which are always write operations used to initiate the command. They are followed by either further write cycles to confirm the first command or execute the command immediately. Command sequencing must be followed exactly. Any invalid combination of com-

mands will reset the device to Read Array. The increased number of cycles has been chosen to assure maximum data security. Commands are initialised by two preceding coded cycles which unlock the Command Interface. In addition, for Erase, command confirmation is again preceeded by the two coded cycles.

P/E.C. status is indicated during command execution by Data Polling on DQ7, detection of Toggle on DQ6, or Error on DQ5 and Erase Timer DQ3 bits. Any read attempt during Program or Erase command execution will automatically output those four bits. The P/E.C. automatically sets bits DQ3, DQ5, DQ6 and DQ7. Other bits (DQ0, DQ1, DQ2 and DQ4) are reserved for future use and should be masked.







#### Figure 5. Memory Map and Sector Address Table

#### Table 11. DC Characteristics

(T<sub>A</sub> = 0 to 70°C, -20 to 85°C, -40 to 85°C or -40 to 125°C; V<sub>CC</sub> = 5V  $\pm$  10%)

Symbol	Parameter	Test Condition	Min	Max	Unit
ILI	Input Leakage Current	$0V \leq V_{IN} \leq V_{CC}$		±1	μA
ILO	Output Leakage Current	$0V \leq V_{\text{OUT}} \leq V_{\text{CC}}$		±1	μA
I <sub>CC1</sub>	Supply Current (Read) TTL	$\overline{E} = V_{IL}, \overline{G} = V_{IH}, f = 6MHz$		40	mA
Icc2	Supply Current (Standby) TTL	Ē = V <sub>IH</sub>		1	mA
I <sub>CC3</sub>	Supply Current (Standby) CMOS	$\overline{E} = V_{CC} \pm 0.2V$		100	μA
I <sub>CC4</sub>	Supply Current (Program or Erase)	Byte program, Sector or Bulk Erase in progress		60	mA
VIL	Input Low Voltage		-0.5	0.8	V
V <sub>IH</sub>	Input High Voltage		2	V <sub>CC</sub> + 0.5	V
Vol	Output Low Voltage	I <sub>OL</sub> = 10mA		0.45	~
	Output High Voltage TTL	I <sub>OH</sub> = –2.5mA	2.4		V
Voh	Output High Voltage CMOS	I <sub>OH</sub> = –100µА	V <sub>CC</sub> -0.4		V
		I <sub>OH</sub> = –2.5mA	0.85 x V <sub>CC</sub>		V
V <sub>ID</sub>	A9 Voltage (Electronic Signature)		11.5	12.5	V
lid	A9 Current (Electronic Signature)	A9 = V <sub>ID</sub>		50	μA
Vlko	Supply Voltage (Erase and Program lock-out)		3.2	4.2	V



#### Table 12A. Read AC Characteristics

(T<sub>A</sub> = 0 to 70°C, -20 to 85°C, -40 to 85°C or -40 to 125°C)

					M29	F040		
				-70 <sup>(3)</sup>			90	
Symbol	Alt	Parameter	Test Condition	V <sub>CC</sub> = !	5V ± 5%	$V_{\rm CC}$ = 5V ± 10%		Unit
				SR. Inter	AM rface	EPR Inter	ROM rface	
				Min	Мах	Min	Мах	
tavav	t <sub>RC</sub>	Address Valid to Next Address Valid	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$	70		90		ns
tavqv	tacc	Address Valid to Output Valid	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$		70		90	ns
t <sub>ELQX</sub> (1)	t <sub>LZ</sub>	Chip Enable Low to Output Transition	G = V <sub>IL</sub>	0		0		ns
t <sub>ELQV</sub> <sup>(2)</sup>	t <sub>CE</sub>	Chip Enable Low to Output Valid	G = V <sub>IL</sub>		70		90	ns
t <sub>GLQX</sub> <sup>(1)</sup>	tolz	Output Enable Low to Output Transition	$\overline{E} = V_{IL}$	0		0		ns
t <sub>GLQV</sub> <sup>(2)</sup>	t <sub>OE</sub>	Output Enable Low to Output Valid	Ē = VIL		30		35	ns
t <sub>EHQX</sub>	t <sub>OH</sub>	Chip Enable High to Output Transition	G = V <sub>IL</sub>	0		0		ns
t <sub>EHQZ</sub> <sup>(1)</sup>	t <sub>HZ</sub>	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$		20		20	ns
t <sub>GHQX</sub>	t <sub>ОН</sub>	Output Enable High to Output Transition	Ē = V <sub>IL</sub>	0		0		ns
t <sub>GHQZ</sub> <sup>(1)</sup>	t <sub>DF</sub>	Output Enable High to Output Hi-Z	Ē = V <sub>IL</sub>		20		20	ns
taxqx	t <sub>он</sub>	Address Transition to Output Transition	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$	0		0		ns

Notes: 1. Sampled only, not 100% tested.

2.  $\overline{G}$  may be delayed by up to  $t_{ELQV}$  -  $t_{GLQV}$  after the falling edge of  $\overline{E}$  without increasing  $t_{ELQV}$ .

3. At grade 1 (0 to 70°C) temperature range

Data Polling Bit DQ7. When Programming operations are in progress, this bit outputs the complement of the bit being programmed on DQ7. During Erase operation, it outputs a '0'. After completion of the operation, DQ7 will output the bit last programmed or a '1' after erasing. Data Polling is valid only effective during P/E.C. operation, that is after the fourth  $\overline{W}$  pulse for programming or after the sixth  $\overline{W}$  pulse for Erase. It must be performed at the address being programmed or at an address within the sector being erased. If the byte to be programmed belongs to a protected sector the command is ignored. If all the sectors selected for erasure are protected, DQ7 will set to '0' for about  $100 \mu s,$  and then return to previous addressed memory data. See Figure 9 for the Data Polling flowchart and Figure 10 for the Data Polling waveforms.

Toggle Bit DQ6. When Programming operations are in progress, successive attempts to read DQ6 will output complementary data. DQ6 will toggle following toggling of either  $\overline{G}$  or  $\overline{E}$  when  $\overline{G}$  is low. The operation is completed when two successive reads yield the same output data. The next read will output the bit last programmed or a '1' after erasing. The toggle bit is valid only effective during P/E.C. operations, that is after the fourth  $\overline{W}$  pulse for programming or after the sixth  $\overline{W}$  pulse for Erase. If the byte to be programmed belongs to a protected sector the command will be ignored. If the sectors selected for erasure are protected, DQ6 will toggle for about 100µs and then return back to Read. See Figure 11 for Toggle Bit flowchart and Figure 12 for Toggle Bit waveforms.



#### Table 12B. Read AC Characteristics

(T<sub>A</sub> = 0 to 70°C, -20 to 85°C, -40 to 85°C or -40 to 125°C)

					M29	F040		
				-120		-1	50	
Symbol	Alt	Parameter	Test Condition	V <sub>CC</sub> = 5	V ± 10%	V <sub>CC</sub> = 5	V ± 10%	Unit
				EPR Inter		EPR Inter	ROM rface	
				Min	Мах	Min	Мах	
tavav	t <sub>RC</sub>	Address Valid to Next Address Valid	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$	120		150		ns
tavqv	tacc	Address Valid to Output Valid	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$		120		150	ns
t <sub>ELQX</sub> (1)	t <sub>LZ</sub>	Chip Enable Low to Output Transition	G = V <sub>IL</sub>	0		0		ns
t <sub>ELQV</sub> <sup>(2)</sup>	t <sub>CE</sub>	Chip Enable Low to Output Valid	G = V <sub>IL</sub>		120		150	ns
t <sub>GLQX</sub> <sup>(1)</sup>	tolz	Output Enable Low to Output Transition	Ē = V <sub>IL</sub>	0		0		ns
t <sub>GLQV</sub> <sup>(2)</sup>	t <sub>OE</sub>	Output Enable Low to Output Valid	Ē = V <sub>IL</sub>		50		55	ns
tEHQX	t <sub>OH</sub>	Chip Enable High to Output Transition	G = V <sub>IL</sub>	0		0		ns
t <sub>EHQZ</sub> <sup>(1)</sup>	t <sub>HZ</sub>	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$		30		35	ns
t <sub>GHQX</sub>	t <sub>ОН</sub>	Output Enable High to Output Transition	Ē = V <sub>IL</sub>	0		0		ns
t <sub>GHQZ</sub> <sup>(1)</sup>	t <sub>DF</sub>	Output Enable High to Output Hi-Z	Ē = V <sub>IL</sub>		30		35	ns
taxqx	t <sub>он</sub>	Address Transition to Output Transition	$\overline{E} = V_{IL}, \ \overline{G} = V_{IL}$	0		0		ns

Notes: 1. <u>Sampled only</u>, not 100% tested.

2.  $\overline{G}$  may be delayed by up to  $t_{ELQV}$  -  $t_{GLQV}$  after the falling edge of  $\overline{E}$  without increasing  $t_{ELQV}$ .

**Error bit DQ5.** This bit is set to '1' by the P/E.C when there is a failure of byte programming, sector erase, or bulk erase that results in invalid data being programmed in the memory sector. In case of error in sector erase or byte program, the sector in which the error occured or to which the programmed byte belongs, must be discarded. Other sectors may still be used. Error bit resets after Reset (RST) instruction. In case of success, the error bit will set to '0' during Program or Erase and to valid data after write operation is completed.

**Erase Timer bit DQ3.** This bit is set to '0' by the P/E.C. when the last sector Erase command has been entered to the Command Interface and it is awaiting the Erase start. When the wait period is finished, after 80 to  $120\mu s$ , DQ3 returns back to '1'.

**Coded Cycles.** The two coded cycles unlock the Command Interface. They are followed by a command input or a comand confirmation. The coded cycles consist of writing the data 0AAh at address 5555h during the first cycle and data 55h at address 2AAAh during the second cycle. Addresses are latched on the falling edge of  $\overline{W}$  or  $\overline{E}$  while data is latched on the rising edge of  $\overline{W}$  or  $\overline{E}$ . The coded cycles happen on first and second cycles of the command write or on the fourth and fifth cycles.

**Reset (RST) instruction.** The Reset instruction consists of one write operation giving the command 0F0h. It can be optionally preceded by the two coded cycles. After wait state of  $5\mu$ s, subsequent read operations will read the memory array addressed and output the read byte.







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### Table 13A. Write AC Characteristics, Write Enable Controlled $(T_{12} = 0.12, 70\%)$ 2010 $(S_{12} = 0.12, 70\%)$

 $(T_A = 0 \text{ to } 70^{\circ}C, -20 \text{ to } 85^{\circ}C, -40 \text{ to } 85^{\circ}C \text{ or } -40 \text{ to } 125^{\circ}C)$ 

				M29	F040		
			-70	) <sup>(2)</sup>		90	
Symbol	Alt	Parameter	V <sub>CC</sub> = 5V ± 5% SRAM Interface		V <sub>CC</sub> = 5V ± 10% EPROM Interface		Unit
			Min	Мах	Min	Max	
t <sub>AVAV</sub>	t <sub>WC</sub>	Address Valid to Next Address Valid	70		90		ns
telwl	tcs	Chip Enable Low to Write Enable Low	0		0		ns
t <sub>WLWH</sub>	t <sub>WP</sub>	Write Enable Low to Write Enable High	35		45		ns
t <sub>DVWH</sub>	t <sub>DS</sub>	Input Valid to Write Enable High	30		45		ns
t <sub>WHDX</sub>	t <sub>DH</sub>	Write Enable High to Input Transition	0		0		ns
t <sub>WHEH</sub>	t <sub>CH</sub>	Write Enable High to Chip Enable High	0		0		ns
t <sub>WHWL</sub>	t <sub>WPH</sub>	Write Enable High to Write Enable Low	20		20		ns
t <sub>AVWL</sub>	t <sub>AS</sub>	Address Valid to Write Enable Low	0		0		ns
t <sub>WLAX</sub>	tан	Write Enable Low to Address Transition	45		45		ns
t <sub>GHWL</sub>		Output Enable High to Write Enable Low	0		0		ns
<b>t</b> vchel	t <sub>VCS</sub>	V <sub>CC</sub> High to Chip Enable Low	50		50		μs
t <sub>WHQV1</sub> <sup>(1)</sup>		Write Enable High to Output Valid (Program)	10		10		μs
t <sub>WHQV2</sub> (1)		Write Enable High to Output Valid (Sector Erase)	1.5	30	1.5	30	sec
t <sub>WHGL</sub>	t <sub>OEH</sub>	Write Enable High to Output Enable Low	0		0		ns

Notes: 1. Time is measured to Data Polling or Toggle Bit, t<sub>WHQV</sub> = t<sub>WHQ7V</sub> + t<sub>Q7VQV</sub> 2. At grade 1 (0 to 70°C) temperature range.

**Read Electronic Signature (RSIG) instruction.** This instruction uses the two coded cycles followed by one write cycle giving the command 90h to address 5555h for command setup. A subsequent read will output the manufacturer code, the device code or the sector protection status depending on the levels of A0, A1, A6, A16, A17 and A18. The manufacturer code, 20h, is output when the addresses lines A0, A1 and A6 are Low, the device code, 0E2h is output when A0 is High with A1 and A6 Low.

**Read Sector Protection.** The use of Read Electronic Signature (RSIG) command also allows access to the sector protection status verify. After giving the RSIG command, A0 and A6 are set to  $V_{IL}$  with A1 at  $V_{IH}$ , while A16, A17 and A18 define the

sector of the sector to be verified. A read in these conditions will output a 01h if sector is protected and a 00h if sector is not protected.

Bulk Erase (BE) instruction. This instruction uses six write cycles. The Erase Set-up command 80h is written to address 5555h on third cycle after the two coded cycles. The Bulk Erase Confirm command 10h is written at address 5555h on sixth cycle after another two coded cycles. If the second command given is not an erase confirm or if the coded cycles are wrong, the instruction aborts and the device is reset to Read Array. It is not necessary to program the array with 00h first as the P/E.C. will automatically do this before erasing to 0FFh. Read operations after the sixth rising edge of  $\overline{W}$  or  $\overline{E}$ output the status register bits. During the execu-



#### Table 13B. Write AC Characteristics, Write Enable Controlled

 $(T_A = 0 \text{ to } 70^{\circ}\text{C}, -20 \text{ to } 85^{\circ}\text{C}, -40 \text{ to } 85^{\circ}\text{C} \text{ or } -40 \text{ to } 125^{\circ}\text{C})$ 

				M29	F040		
0		Bananatan	-1	20	-1	50	11
Symbol	Alt	Parameter	V <sub>CC</sub> = 5	V ± 10%	$V_{\rm CC}$ = 5V $\pm$ 10%		Unit
			EPROM Interface		EPROM Interface		
			Min	Мах	Min	Мах	
t <sub>AVAV</sub>	t <sub>WC</sub>	Address Valid to Next Address Valid	120		150		ns
telwl	tcs	Chip Enable Low to Write Enable Low	0		0		ns
t <sub>VVLVVH</sub>	t <sub>WP</sub>	Write Enable Low to Write Enable High	50		50		ns
<b>t</b> D∨WH	t <sub>DS</sub>	Input Valid to Write Enable High	50		50		ns
t <sub>WHDX</sub>	t <sub>DH</sub>	Write Enable High to Input Transition	0		0		ns
t <sub>WHEH</sub>	t <sub>CH</sub>	Write Enable High to Chip Enable High	0		0		ns
t <sub>WHWL</sub>	t <sub>WPH</sub>	Write Enable High to Write Enable Low	20		20		ns
t <sub>AVWL</sub>	t <sub>AS</sub>	Address Valid to Write Enable Low	0		0		ns
twlax	tан	Write Enable Low to Address Transition	50		50		ns
t <sub>GHWL</sub>		Output Enable High to Write Enable Low	0		0		ns
<b>t</b> vchel	t <sub>VCS</sub>	V <sub>CC</sub> High to Chip Enable Low	50		50		μs
t <sub>WHQV1</sub> (1)		Write Enable High to Output Valid (Program)	10		10		μs
t <sub>WHQV2</sub> (1)		Write Enable High to Output Valid (Sector Erase)	1.5	30	1.5	30	sec
t <sub>WHGL</sub>	t <sub>OEH</sub>	Write Enable High to Output Enable Low	0		0		ns

Note: 1. Time is measured to Data Polling or Toggle Bit,  $t_{WHQV} = t_{WHQ7V} + t_{Q7VQV}$ 

#### **DEVICE OPERATION** (cont'd)

tion of the erase by the P/E.C. the memory accepts only the Reset (RST) command. Read of Data Polling bit DQ7 returns '0', then '1' on completion. The Toggle Bit DQ6 toggles during erase operation and stops when erase is completed. After completion the Status Register bit DQ5 returns '1' if there has been an Erase Failure because the erasure has not been verified even after the maximum number of erase cycles have been executed.

Sector Erase (SE) instruction. This instruction uses a minimum of six write cycles. The Erase Set-up command 80h is written to address 5555h on third cycle after the two coded cycles. The Sector Erase Confirm command 30h is written on sixth cycle after another two coded cycles. During the input of the second command an address within the sector to be erased is given and latched into the memory. Additional Sector Erase confirm commands and sector addresses can be written subsequently to erase other sectors in parallel, without further coded cycles. The erase will start after an Erase timeout period of about 100µs. Thus, additional Sector Erase commands must be given within this delay. The input of a new Sector Erase command will restart the timeout period. The status of the internal timer can be monitored through the level of DQ3, if DQ3 is '0' the Sector Erase Command has been given and the timeout is running, if DQ3 is '1', the timeout has expired and the P/E.C is erasing the sector(s). Before and during Erase timeout, any command different from 30h will abort the instruction and reset the device to read array mode. It is not necessary to program the sector with 00h as the P/E.C. will do this auto-



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Figure 7. Write AC Waveforms, W Controlled

Note: Address are latched on the falling edge of  $\overline{W}$ , Data is latched on the rising edge of  $\overline{W}$ .

matically before to erasing to 0FFh. Read operations after the sixth rising edge of  $\overline{W}$  or  $\overline{E}$  output the status register status bits.

During the execution of the erase by the P/E.C., the memory accepts only the ES (Erase Suspend) and RST (Reset) instructions. Data Polling bit DQ7 returns '0' while the erasure is in progress and '1' when it has completed. The Toggle Bit DQ6 toggles during the erase operation. It stops when erase is completed. After completion the Status Register bit DQ5 returns '1' if there has been an Erase Failure because erasure has not completed even after the maximum number of erase cycles have been executed. In this case, it will be necessary to input a Reset (RST) to the command interface in order to reset the P/E.C.

**Program (PG) instruction.** This instruction uses four write cycles. The Program command A0h is written on the third cycle after two coded cycles. A fourth write operation latches the Address on the

falling edge of  $\overline{W}$  or  $\overline{E}$  and the Data to be written on its rising edge and starts the P/E.C. During the execution of the program by the P/E.C., the memory will not accept any instruction. Read operations output the status bits after the programming has started. Memory programming is made only by writing '0' in place of '1' in a Byte.

**Erase Suspend (ES) instruction.** The Sector Erase operation may be suspended by this instruction which consists of writing the command 0B0h without any specific address code. No coded cycles are required. It allows reading of data from another sector while erase is in progress. Erase suspend is accepted only during the Sector Erase instruction execution and defaults to read array mode. Writing this command during Erase timeout will, in addition to suspending the erase, terminate the timeout. The Toggle Bit DQ6 stops toggling when the P/E.C. is suspended. Toggle Bit status must be monitored at an address out of the sector being erased.



#### Table 14A. Write AC Characteristics, Chip Enable Controlled

 $(T_A = 0 \text{ to } 70^{\circ}\text{C}, -20 \text{ to } 85^{\circ}\text{C}, -40 \text{ to } 85^{\circ}\text{C} \text{ or } -40 \text{ to } 125^{\circ}\text{C})$ 

				M29	F040			
	•••		-70	) <sup>(2)</sup>		90	•• ••	
Symbol	Alt	Parameter	<b>V</b> <sub>CC</sub> = 4	5V ± 5%	$V_{CC}$ = 5V ± 10%		Unit	
			SRAM Interface		EPROM Interface			
			Min	Max	Min	Мах		
t <sub>AVAV</sub>	t <sub>WC</sub>	Address Valid to Next Address Valid	70		90		ns	
t <sub>WLEL</sub>	tws	Write Enable Low to Chip Enable Low	0		0		ns	
t <sub>ELEH</sub>	t <sub>CP</sub>	Chip Enable Low to Chip Enable High	35		45		ns	
<b>t</b> DVEH	tos	Input Valid to Chip Enable High	30		45		ns	
t <sub>EHDX</sub>	t <sub>DH</sub>	Chip Enable High to Input Transition	0		0		ns	
t <sub>EHWH</sub>	t <sub>WH</sub>	Chip Enable High to Write Enable High	0		0		ns	
t <sub>EHEL</sub>	t <sub>CPH</sub>	Chip Enable High to Chip Enable Low	20		20		ns	
t <sub>AVEL</sub>	t <sub>AS</sub>	Address Valid to Chip Enable Low	0		0		ns	
<b>t</b> elax	<b>t</b> AH	Chip Enable Low to Address Transition	45		45		ns	
t <sub>GHEL</sub>		Output Enable High Chip Enable Low	0		0		ns	
tvcнw∟	tvcs	V <sub>CC</sub> High to Write Enable Low	50		50		ns	
t <sub>EHQV1</sub> <sup>(1)</sup>		Chip Enable High to Output Valid (Program)	10		10		μs	
t <sub>EHQV2</sub> <sup>(1)</sup>		Chip Enable High to Output Valid (Sector Erase)	1.5	30	1.5	30	sec	
t <sub>EHGL</sub>	t <sub>OEH</sub>	Chip Enable High to Output Enable Low	0		0		ns	

Notes: 1. Time is measured to Data Polling or Toggle Bit, t<sub>WHQV</sub> = t<sub>WHQ7V</sub> + t<sub>Q7VQV</sub> 2. At grade 1 (0 to 70°C) temperature range.

#### DEVICE OPERATION (cont'd)

Toggle Bit will stop toggling between 0.1µs and 15µs after the Erase Suspend (ES) command has been written. The M29F040 will then automatically set to Read Memory Array mode. When erase is suspended, Read from sectors being erased will output invalid data, Read from sector not being erased is valid. During the suspension the memory will respond only to Erase Resume (ER) and Reset (RST) instructions. RST command will definitively abort erasure and result in the invalid data in the sectors being erased.

**Erase Resume (ER) instruction.** If an Erase Suspend instruction was previously executed, the erase operation may be resumed by giving the command 30h, at any address, and without any coded cycles.

**Programing.** The memory can be programmed byte-by-byte. The program sequence is started by the two coded cycles, followed by writing the Program command (0A0h) to the Command Interface. This is followed by writing the address and data byte to the memory. The Program/Erase Controller automatically starts and performs the programming after the fourth write operation. During programming the memory status is checked by reading the status bits DQ5, DQ6 and DQ7 which show the status of the P/E.C. DQ6 and DQ7 determine if programming is on going or has completed and DQ5 allows a check to be made for any possible error.



## Table 14B. Write AC Characteristics, Chip Enable Controlled ( $T_A = 0$ to 70°C, -20 to 85°C, -40 to 85°C or -40 to 125°C)

M29F040 -120 -150 Symbol Alt Parameter Unit  $V_{\rm CC}$  = 5V ± 10%  $V_{\rm CC}$  = 5V  $\pm$  10% **EPROM Interface EPROM Interface** Min Max Min Max 120 150 Address Valid to Next Address Valid ns t\_\/A\/ two Write Enable Low to Chip Enable Low 0 0 tWLEL tws ns Chip Enable Low to Chip Enable High 50 50 t<sub>ELEH</sub> t<sub>CP</sub> ns 50 50 Input Valid to Chip Enable High **t**dveh tos ns Chip Enable High to Input Transition 0 0 **t**EHDX tDH ns 0 0 Chip Enable High to Write Enable High t<sub>EHWH</sub> t<sub>WH</sub> ns Chip Enable High to Chip Enable Low 20 20 **t**EHEL t<sub>CPH</sub> ns 0 0 Address Valid to Chip Enable Low **t**AVEL t<sub>AS</sub> ns Chip Enable Low to Address Transition 50 50 **t**ELAX tан ns 0 0 **t**GHEL Output Enable High Chip Enable Low ns t<sub>VCHWL</sub> tvcs V<sub>CC</sub> High to Write Enable Low 50 50 ns  $t_{\text{EHQV1}}\,{}^{(1)}$ Chip Enable High to Output Valid (Program) 10 10 μs Chip Enable High to Output Valid  $t_{EHQV2}$ <sup>(1)</sup> 1.5 30 1.5 30 sec (Sector Erase) 0 0 Chip Enable High to Output Enable Low ns t<sub>OEH</sub> t<sub>EHGI</sub>

**Note:** 1. Time is measured to Data Polling or Toggle Bit,  $t_{WHQV} = t_{WHQ7V} + t_{Q7VQV}$ 

#### **Power Up**

The memory Command Interface is reset on power up to Read Array. Either  $\overline{E}$  or  $\overline{W}$  must be tied to V<sub>IH</sub> during Power-up to allow maximum security and the possibility to write a command on the first rising adge of  $\overline{E}$  or  $\overline{W}$ . Any write cycle initiation is blocked when V<sub>CC</sub> is below V<sub>LKO</sub>.

#### **Supply Rails**

Normal precautions must be taken for supply voltage decoupling, each device in a system should have the V<sub>CC</sub> rail decoupled with a 0.1 $\mu$ F capacitor close to the V<sub>CC</sub> and V<sub>SS</sub> pins. The PCB trace widths should be sufficient to carry the V<sub>CC</sub> program and erase currents required.





Figure 8. Write AC Waveforms, E Controlled

Note: Address are latched on the falling edge of  $\overline{E}$ , Data is latched on the rising edge of  $\overline{E}$ .



#### Table 15A. Data Polling and Toggle Bit AC Characteristics (1) $(T_A = 0 \text{ to } 70^{\circ}\text{C}, -20 \text{ to } 85^{\circ}\text{C}, -40 \text{ to } 85^{\circ}\text{C} \text{ or } -40 \text{ to } 125^{\circ}\text{C})$

M29F040 -70 (3) -90 Symbol Alt Parameter Unit  $V_{\rm CC}$  = 5V ± 5%  $V_{\rm CC}$  = 5V  $\pm$  10% **SRAM Interface EPROM Interface** Min Мах Min Мах Write Enable High to DQ7 Valid  $t_{\text{WHQ7V1}} \ ^{(2)}$ 10 10 μs (Program, W Controlled) Write Enable High to DQ7 Valid t<sub>WHQ7V2</sub> (2) 1.5 30 1.5 30 sec (Sector Erase, W Controlled) Chip Enable High to DQ7 Valid  $t_{\text{EHQ7V1}}$  (2) 10 10 μs (Program, E Controlled) Chip Enable High to DQ7 Valid (Sector Erase, E Controlled) t<sub>EHQ7V2</sub> (2) 1.5 30 1.5 30 sec Q7 Valid to Output Valid (Data Polling) 30 35 t<sub>Q7VQV</sub> ns Write Enable High to Output Valid 10 10 twhqv1 μs (Program) Write Enable High to Output Valid 1.5 30 1.5 30 sec t<sub>WHQV2</sub> (Sector Erase) Chip Enable High to Output Valid 10 10 t<sub>FHOV1</sub> μs (Program) Chip Enable High to Output Valid 1.5 30 1.5 30 sec t<sub>EHQV2</sub> (Sector Erase)

Notes: 1. All other timings are defined in Read AC Characteristics table. 2. twharv is the Program or Erase time. 3. At grade 1 (0 to 70°C) temperature range.



# Table 15B. Data Polling and Toggle Bit AC Characteristics <sup>(1)</sup> (T<sub>A</sub> = 0 to 70°C, -20 to 85°C, -40 to 85°C or -40 to 125°C)

				M 29	F040		
Sumbol	Alt	Parameter	-1	20	1:	50	Unit
Symbol	AIL	Falameter	V <sub>CC</sub> = 5	V ± 10%	V <sub>CC</sub> = 5V ± 10% EPROM Interface		
			EPROM	Interface			
			Min	Max	Min	Max	
t <sub>WHQ7V1</sub> <sup>(2)</sup>		Write Enable High to DQ7 Valid (Program, W Controlled)	10		10		ms
twhq7v2 (2)		Write Enable H <u>ig</u> h to DQ7 Valid (Sector Erase, W Controlled)	1.5	30	1.5	30	sec
t <sub>EHQ7V1</sub> (2)		Chip Enabl <u>e</u> High to DQ7 Valid (Program, E Controlled)	10		10		ms
t <sub>EHQ7V2</sub> <sup>(2)</sup>		Chip Enable Hi <u>a</u> h to DQ7 Valid (Sector Erase, E Controlled)	1.5	30	1.5	30	sec
<b>t</b> q7vqv		Q7 Valid to Output Valid (Data Polling)		50		55	ns
t <sub>WHQV1</sub>		Write Enable High to Output Valid (Program)	10		10		μs
t <sub>WHQV2</sub>		Write Enable High to Output Valid (Sector Erase)	1.5	30	1.5	30	sec
t <sub>EHQV1</sub>		Chip Enable High to Output Valid (Program)	10		10		μs
t <sub>EHQV2</sub>		Chip Enable High to Output Valid (Sector Erase)	1.5	30	1.5	30	sec

Notes: 1. All other timings are defined in Read AC Characteristics table. 2. twhorv is the Program or Erase time.





#### Figure 9. Data Polling DQ7 AC Waveforms

#### M29F040



Table 16. Program, Erase Times and Program, Erase Endurance Cycles (T\_A = 0 to 70°C; V\_{CC} = 5V  $\pm$  10% or 5V  $\pm$  5%)

Parameter		M29F040		Unit
	Min	Тур	Мах	Onit
Chip Program (Byte)		6		sec
Bulk Erase (Preprogrammed)		2.5	30	sec
Bulk Erase		8.5		sec
Sector Erase (Preprogrammed)		1	30	sec
Sector Erase		1.5		sec
Byte Program	10		1200	μs
Program/Erase Cycles (per Sector)	100,000			cycles





Figure 12. Data Toggle DQ6 AC Waveforms

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Figure 14. Sector Unprotecting Flow-chart

Note: 1. A6 is kept at V<sub>IH</sub> during unprotection algorithm in order to secure best unprotection verification. During all other protection status reads, A6 must be kept at V<sub>IL</sub>.



#### **ORDERING INFORMATION SCHEME**



For a list of available options ( $V_{CC}$  Range, Speed, etc...) refer to the current Memory Shortform catalogue. For further information on any aspect of this device, please contact the SGS-THOMSON Sales Office nearest to you.



Symb		mm			inches	
Symb	Тур	Min	Мах	Тур	Min	Мах
А		2.54	3.56		0.100	0.140
A1		1.52	2.41		0.060	0.095
В		0.33	0.53		0.013	0.021
B1		0.66	0.81		0.026	0.032
D		12.32	12.57		0.485	0.495
D1		11.35	11.56		0.447	0.455
D2		9.91	10.92		0.390	0.430
E		14.86	15.11		0.585	0.595
E1		13.89	14.10		0.547	0.555
E2		12.45	13.46		0.490	0.530
е	1.27	-	-	0.050	-	_
N		32			32	
Nd		7			7	
Ne		9			9	
СР			0.10			0.004

## PLCC32 - 32 lead Plastic Leaded Chip Carrier, rectangular

PLCC32







Symb		mm		inches			
e y	Тур	Min	Мах	Тур	Min	Max	
А			1.20			0.047	
A1		0.05	0.17		0.002	0.006	
A2		0.95	1.50		0.037	0.059	
В		0.15	0.27		0.006	0.011	
С		0.10	0.21		0.004	0.008	
D		19.80	20.20		0.780	0.795	
D1		18.30	18.50		0.720	0.728	
E		7.90	8.10		0.311	0.319	
е	0.50	-	-	0.020	-	-	
L		0.50	0.70		0.020	0.028	
α		<b>0</b> °	5°		<b>0</b> °	5°	
N		32			32		

## TSOP32 Normal Pinout - 32 lead Plastic Thin Small Outline, 8 x 20mm

TSOP32



Drawing is not to scale



Symb		mm		inches			
eynio	Тур	Min	Max	Тур	Min	Мах	
А			1.20			0.047	
A1		0.05	0.17		0.002	0.006	
A2		0.95	1.50		0.037	0.059	
В		0.15	0.27		0.006	0.011	
С		0.10	0.21		0.004	0.008	
D		19.80	20.20		0.780	0.795	
D1		18.30	18.50		0.720	0.728	
E		7.90	8.10		0.311	0.319	
е	0.50	-	-	0.020	_	_	
L		0.50	0.70		0.020	0.028	
α		<b>0</b> °	5°		0°	5°	
N		32			32		
СР			0.10			0.004	

## TSOP32 Reverse Pinout - 32 lead Plastic Thin Small Outline, 8 x 20mm

TSOP32



Drawing is not to scale



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